Amendments to the Claims

This version of the claims replaces all previous versions.

Please amend claims 15, 18 and 23 as shown.

Please add new claims 28-40.

Claims 1-14 (canceled).

15 (currently amended): A heat-resistant fiber impregnated material which retains at least 70% of its tensile strength when left in an environment at 200° C for one hour, comprising heat-resistant fibers impregnated with a polyimide binder resin,
wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor,
has a glass transition temperature of 190-350° C and
consists ~~essentially~~ of a tetracarboxylic acid component and an aromatic diamine component.

16 (previously presented): The heat-resistant fiber impregnated material according to claim 15, wherein the polyimide binder resin is amorphous based on X-ray analysis.

17 (previously presented): The heat-resistant fiber impregnated material according to claim 15, wherein the tetracarboxylic acid component comprises at least 50% of a 2,3,3',4'-biphenyltetracarboxylic acid component .

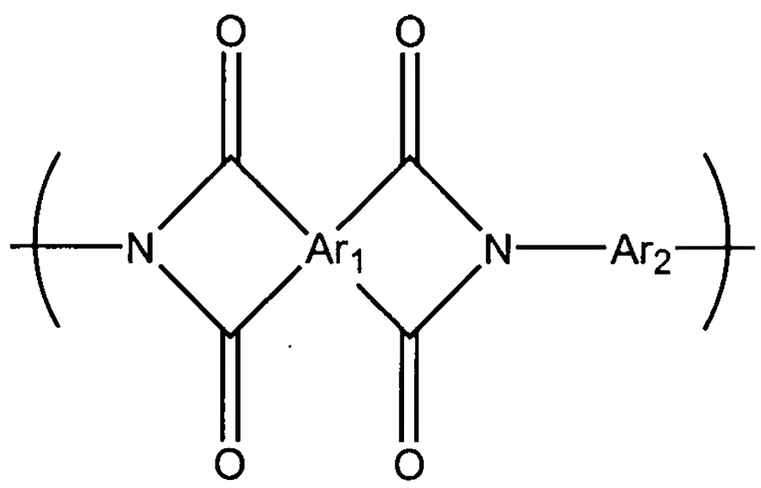
18 (currently amended): A heat-resistant fiber impregnated material comprising heat-resistant fibers impregnated with a polyimide binder resin,
wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor containing 1,2-dimethylimidazole and/or 1-methyl-2-ethylimidazole,
has a glass transition temperature of 190-350° C and
consists ~~essentially~~ of a tetracarboxylic acid component and an aromatic diamine component.

19 (previously presented): The heat-resistant fiber impregnated material according to claim 18, wherein the polyimide binder resin is amorphous, based on X-ray analysis.

20 (previously presented): The heat-resistant fiber impregnated material according to claim 18, wherein the tetracarboxylic acid component comprises at least 50% of a 2,3,3',4'-biphenyltetracarboxylic acid component .

21 (previously presented): A prepreg prepared by further impregnating the heat-resistant fiber impregnated material according to claim 18 with a heat-bonding polyimide.

22 (previously presented): The prepreg according to claim 21, wherein the heat-bonding polyimide is a polyimide with an imide unit represented by the following formula:



wherein Ar_1 is an aromatic tetracarboxylic dianhydride residue, comprising 3,3',4,4'-biphenyltetracarboxylic dianhydride residue and 2,3,3',4'-biphenyltetracarboxylic dianhydride residue in a molar ratio of 0:100-90:10, and Ar_2 is an aromatic diamine residue comprising 1,3-bis(4-aminophenoxy)benzene or 1,3-bis(3-aminophenoxy)benzene and at least one of p-phenylenediamine and diaminodiphenylether in a molar ratio of 10:90-100:0.

23 (currently amended): A prepreg prepared by impregnating a heat-resistant fiber impregnated material with a heat-bonding polyimide,
wherein the heat-resistant fiber impregnated material comprises heat-resistant fibers impregnated with a polyimide binder resin, and

wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor,
has a thermal decomposition temperature of 500° C or higher and a breaking elongation of 15% or greater when shaped into a film and a glass transition temperature of 190-350° C and consists ~~essentially~~ of a tetracarboxylic acid component and an aromatic diamine component.

24 (previously presented): A laminate prepared by bonding a conductive metal layer onto the prepreg according to claim 21.

25 (previously presented): The laminate according to claim 24, wherein the metal layer is a copper foil.

26 (previously presented): A laminate prepared by bonding a conductive metal layer onto the prepreg according to claim 23.

27 (previously presented): The laminate according to claim 26, wherein the metal layer is a copper foil.

28 (new): A heat-resistant fiber impregnated material which retains at least 70% of its tensile strength when left in an environment at 200° C for one hour, comprising heat-resistant fibers impregnated with a polyimide binder resin,
wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor,
has a glass transition temperature of 190-350° C,
comprises a tetracarboxylic acid component and an aromatic diamine component and
is not crosslinked.

29 (new): The heat-resistant fiber impregnated material according to claim 28, wherein the polyimide binder resin is amorphous based on X-ray analysis.

30 (new): The heat-resistant fiber impregnated material according to claim 28, wherein the tetracarboxylic acid component comprises at least 50% of a 2,3,3',4'-biphenyltetracarboxylic acid component .

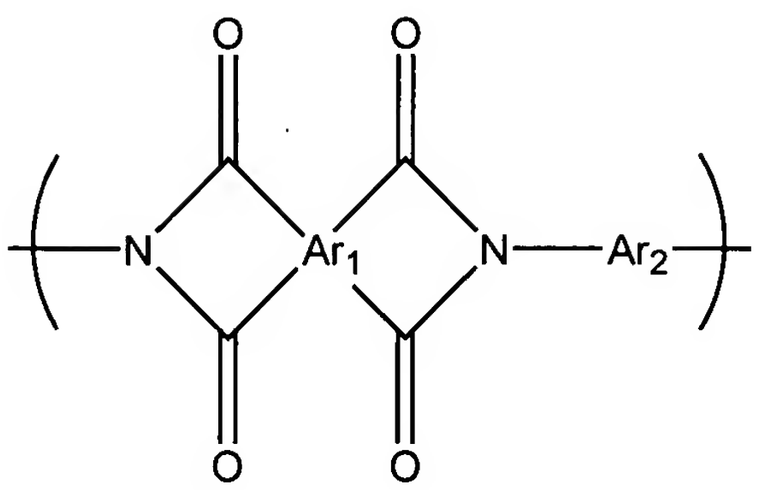
31 (new): A heat-resistant fiber impregnated material comprising heat-resistant fibers impregnated with a polyimide binder resin,
wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor containing 1,2-dimethylimidazole and/or 1-methyl-2-ethylimidazole,
has a glass transition temperature of 190-350° C,
comprises a tetracarboxylic acid component and an aromatic diamine component and
is not crosslinked.

32 (new): The heat-resistant fiber impregnated material according to claim 31, wherein the polyimide binder resin is amorphous, based on X-ray analysis.

33 (new): The heat-resistant fiber impregnated material according to claim 31, wherein the tetracarboxylic acid component comprises at least 50% of a 2,3,3',4'-biphenyltetracarboxylic acid component .

34 (new): A prepreg prepared by further impregnating the heat-resistant fiber impregnated material according to claim 31 with a heat-bonding polyimide.

35 (new): The prepreg according to claim 34, wherein the heat-bonding polyimide is a polyimide with an imide unit represented by the following formula:



wherein Ar_1 is an aromatic tetracarboxylic dianhydride residue, comprising 3,3',4,4'-biphenyltetracarboxylic dianhydride residue and 2,3,3',4'-biphenyltetracarboxylic dianhydride residue in a molar ratio of 0:100-90:10, and Ar_2 is an aromatic diamine residue comprising 1,3-bis(4-aminophenoxy)benzene or 1,3-bis(3-aminophenoxy)benzene and at least one of p-phenylenediamine and diaminodiphenylether in a molar ratio of 10:90-100:0.

36 (new): A prepreg prepared by impregnating a heat-resistant fiber impregnated material with a heat-bonding polyimide,
wherein the heat-resistant fiber impregnated material comprises heat-resistant fibers impregnated with a polyimide binder resin, and
wherein the polyimide binder resin:
is obtained from a water-soluble polyimide precursor,
has a thermal decomposition temperature of 500° C or higher and a breaking elongation of 15% or greater when shaped into a film and a glass transition temperature of 190-350° C,
comprises a tetracarboxylic acid component and an aromatic diamine component and
is not crosslinked.

37 (new): A laminate prepared by bonding a conductive metal layer onto the prepreg according to claim 34.

38 (new): The laminate according to claim 37, wherein the metal layer is a copper foil.

39 (new): A laminate prepared by bonding a conductive metal layer onto the prepreg according to claim 36.

40 (new): The laminate according to claim 39, wherein the metal layer is a copper foil.